



## DESCRIPTION

The TT1300 series are large-geometry, 4-transistor, monolithic NPN and/or PNP arrays exhibiting both high speed and low noise, with excellent parameter matching between transistors of the same gender. With typical base-spreading resistances of 25 ohms for the PNP devices (30 ohms for the NPNs), their resulting low voltage noise of under 1 nV/root-Hz makes the TT1300 ideally suited for low-noise amplifier input stages, among other applications.

Fabricated in a dielectrically isolated, complementary bipolar process, each transistor is electrically insulated from the others by a layer of insulating oxide (not the reverse-biased PN junctions used in conventional arrays) and exhibit inter-device crosstalk and DC isolation similar to that expected from discrete transistors. The resulting low collector-to-substrate capacitance produces a typical NPN  $f_T$  of 350 MHz (325 MHz for the PNPs). Substrate biasing is not required for normal operation, though the substrate should be grounded to optimize speed and minimize crosstalk.

An eight-transistor bare-die array with similar performance characteristics is also available from TT Semiconductor. Please contact us directly or through your sales representative for more information.

## FEATURES

- 4 Matched NPN Transistors (TT1300)
- 4 Matched PNP Transistors (TT1320)
- 2 Matched NPNs and PNPs (TT1340)

Monolithic Construction

Low Noise

- $0.75 \text{ nV}/\sqrt{\text{Hz}}$  (PNP)
- $0.8 \text{ nV}/\sqrt{\text{Hz}}$  (NPN)

High Speed

- $f_T = 350 \text{ MHz}$  (NPN)
- $f_T = 325 \text{ MHz}$  (PNP)

Excellent Matching – 500  $\mu\text{V}$  typical between devices of same gender

Dielectrically Isolated for low crosstalk and high DC isolation

36V  $V_{CEO}$

## APPLICATIONS

Microphone Preamplifiers

Current Sources

Current Mirrors

Log/Antilog Amplifiers

Multipliers

Servos

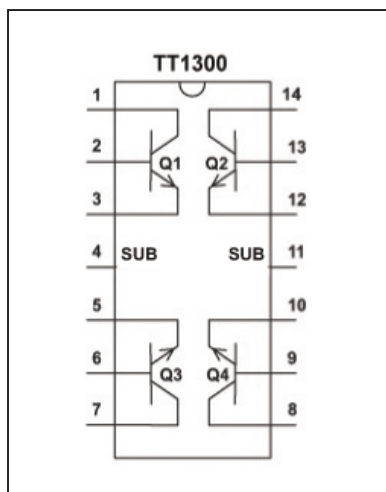


Fig 1. TT1300 Pinout

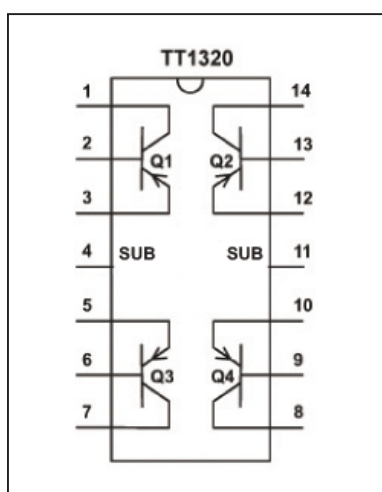


Fig 2. TT1320 Pinout

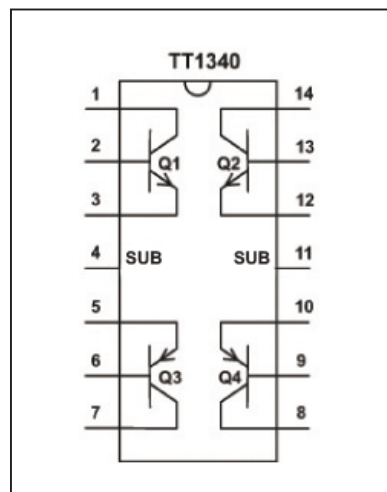


Fig 3. TT1340 Pinout

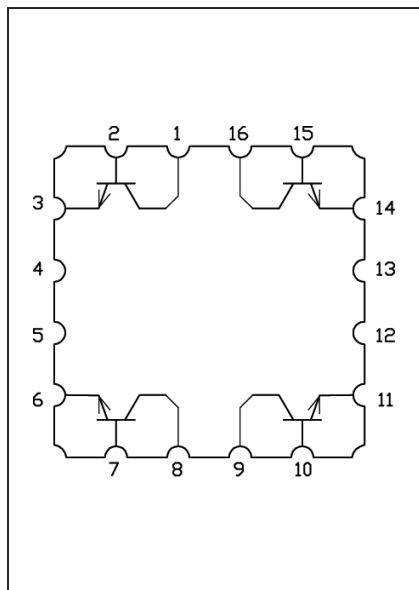


Fig 4. TT1300 LCC Pinout

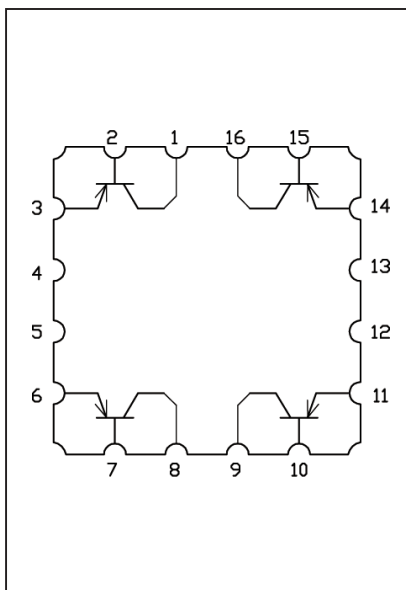


Fig 5. TT1320 LCC Pinout

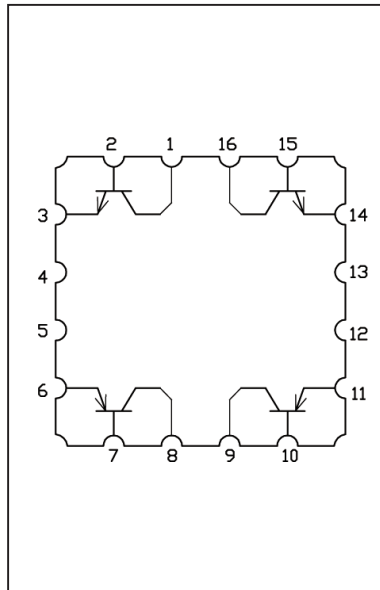


Fig 6. TT1340 LCC Pinout

Maximum Ratings ( $T_A = 25^\circ\text{C}$ )						
Parameter	Symbol	Conditions	Min	Typ	Max	Units
NPN Collector-Emitter Voltage	$BV_{CEO}$	$I_C = 1 \text{ mAdc}$ , $I_B = 0$	36	40	—	V
NPN Collector-Base Voltage	$BV_{CBO}$	$I_C = 10 \text{ Adc}$ , $I_E = 0$	36	40	—	V
NPN Emitter-Base Voltage	$BV_{EBO}$	$I_E = 100 \text{ Adc}$ , $I_C = 0$	5	—	—	V
NPN Collector Current	$I_{C \text{ MAX}}$		10	20		mA
NPN Emitter Current	$I_{E \text{ MAX}}$		10	20		mA
PNP Collector-Emitter Voltage	$BV_{CEO}$	$I_C = 1 \text{ mAdc}$ , $I_B = 0$	-36	-40	—	V
PNP Collector-Base Voltage	$BV_{CBO}$	$I_C = 10 \text{ Adc}$ , $I_E = 0$	-36	-40	—	V
PNP Emitter-Base Voltage	$BV_{EBO}$	$I_E = 100 \text{ Adc}$ , $I_C = 0$	-5	—	—	V
PNP Collector Current	$I_{C \text{ MAX}}$		-10	-20		mA
PNP Emitter Current	$I_{E \text{ MAX}}$		-10	-20		mA
Collector-Collector Voltage	$BV_{CC}$		100	200	—	V
Emitter-Emitter Voltage	$BV_{EE}$		100	200	—	V
Operating Temperature Range	$T_A$		0		70	$^\circ\text{C}$
Storage Temperature	$T_{\text{STORE}}$		-45		125	$^\circ\text{C}$

NPN Electrical Characteristics						
Parameter	Symbol	Conditions	Min	Typ	Max	Units
NPN Current Gain	$h_{fe}$	$V_{CB} = 10\text{ V}$ $I_C = 1\text{ mA}$ $I_C = 10\text{ A}$	60	100 100	—	—
NPN Current Gain Matching	$h_{fe}$	$V_{CB} = 10\text{ V}, I_C = 1\text{ mA}$	—	5	—	%
NPN Noise Voltage Density	$e_N$	$V_{CB} = 10\text{ V}, I_C = 1\text{ mA}, 1\text{ kHz}$	—	0.8	—	$\text{nV}/\sqrt{\text{Hz}}$
NPN Gain-Bandwidth Product	$f_T$	$I_C = 1\text{ mA}, V_{CB} = 10\text{ V}$	—	350	—	MHz
NPN $V_{BE}$ (TT1300: $V_{BE1}-V_{BE2}, V_{BE3}-V_{BE4}$ ) (TT1340: $V_{BE1}-V_{BE2}$ )	$V_{OS}$	$I_C = 1\text{ mA}$ $I_C = 10\text{ A}$	— —	0.5 0.5	3	mV mV
NPN $I_B$ (TT1300: $I_{B1}-I_{B2}, I_{B3}-I_{B4}$ ) (TT1340: $I_{B1}-I_{B2}$ )	$I_{OS}$	$I_C = 1\text{ mA}$ $I_C = 10\text{ A}$	— —	500 5	1500	nA nA
NPN Collector-Base Leakage Current	$I_{CBO}$	$V_{CB} = 25\text{ V}$	—	25	—	pA
NPN Bulk Resistance	$r_{BE}$	$V_{CB} = 0\text{ V}, 10\text{ A} < I_C < 10\text{ mA}$	—	2	—	—
NPN Base Spreading Resistance	$r_{bb}$	$V_{CB} = 10\text{ V}, I_C = 1\text{ mA}$	—	30	—	—
NPN Collector Saturation Voltage	$V_{CE(SAT)}$	$I_C = 1\text{ mA}, I_B = 100\text{ A}$	—	0.05	—	V
NPN Output Capacitance	$C_{OB}$	$V_{CB} = 10\text{ V}, I_E = 0\text{ mA}, 100\text{ kHz}$	—	3	—	pF
NPN Collector-Collector Capacitance (TT1300: Q1-Q2, Q3-Q4) (TT1340: Q1-Q2)	$C_{CC}$	$V_{CC} = 0\text{ V}, 100\text{ kHz}$	—	0.7	—	pF

1. All specifications subject to change without notice.

PNP Electrical Characteristics						
Parameter	Symbol	Conditions	Min	Typ	Max	Units
PNP Current Gain	$h_{fe}$	$V_{CB} = 10\text{ V}$ $I_C = 1\text{ mA}$ $I_C = 10\text{ A}$	50	75 75	— —	
PNP Current Gain Matching	$h_{fe}$	$V_{CB} = 10\text{ V}, I_C = 1\text{ mA}$	—	5	—	%
PNP Noise Voltage Density	$e_N$	$V_{CB} = 10\text{ V}, I_C = 1\text{ mA}, 1\text{ kHz}$	—	0.75	—	$\text{nV}/\sqrt{\text{Hz}}$
PNP Gain-Bandwidth Product	$f_T$	$I_C = 1\text{ mA}, V_{CB} = 10\text{ V}$		325		MHz
PNP $V_{BE}$ (TT1320: $V_{BE1}-V_{BE2}, V_{BE3}-V_{BE4}$ ) (TT1340: $V_{BE3}-V_{BE4}$ )	$V_{OS}$	$I_C = 1\text{ mA}$ $I_C = 10\text{ A}$	— —	0.5 0.5	3	mV mV
PNP $I_B$ (TT1320: $I_{B1}-I_{B2}, I_{B3}-I_{B4}$ ) (TT1340: $I_{B3}-I_{B4}$ )	$I_{OS}$	$I_C = 1\text{ mA}$ $I_C = 10\text{ A}$	— —	700 7	1800	nA nA
PNP Collector-Base Leakage Current	$I_{CBO}$	$V_{CB} = 25\text{ V}$	—	−25	—	pA
PNP Bulk Resistance	$r_{BE}$	$V_{CB} = 0\text{ V}, 10\text{ A} < I_C < 10\text{ mA}$	—	2	—	
PNP Base Spreading Resistance	$r_{bb}$	$V_{CB} = 10\text{ V}, I_C = 1\text{ mA}$	—	25	—	
PNP Collector Saturation Voltage	$V_{CE(SAT)}$	$I_C = 1\text{ mA}, I_B = 100\text{ A}$	—	−0.05		V
PNP Output Capacitance	$C_{OB}$	$V_{CB} = 10\text{ V}, I_E = 0\text{ mA}, 100\text{ kHz}$		3		pF
PNP Collector-Collector Capacitance (TT1320: Q1-Q2; Q3-Q4) (TT1340: Q3-Q4)	$C_{CC}$	$V_{CC} = 0\text{ V}, 100\text{ kHz}$		0.6		pF

1. All specifications subject to change without notice.

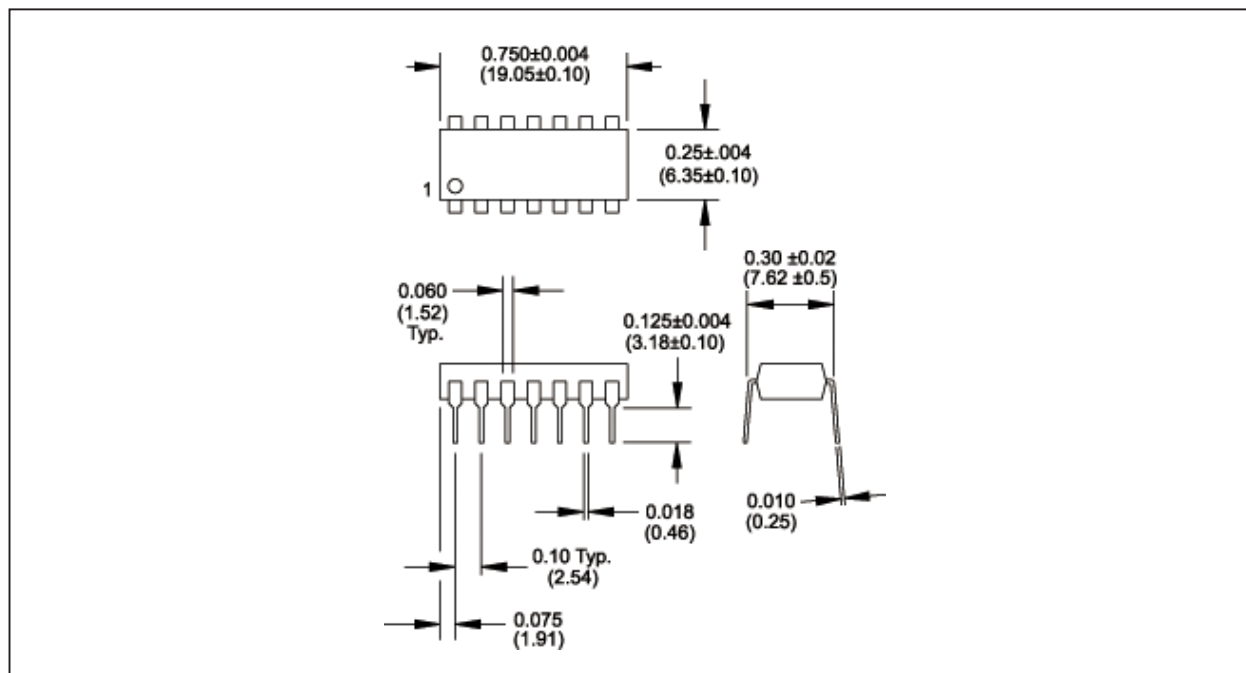


Figure 7. Plastic Extended Temperature Dual-in-Line Package Outline

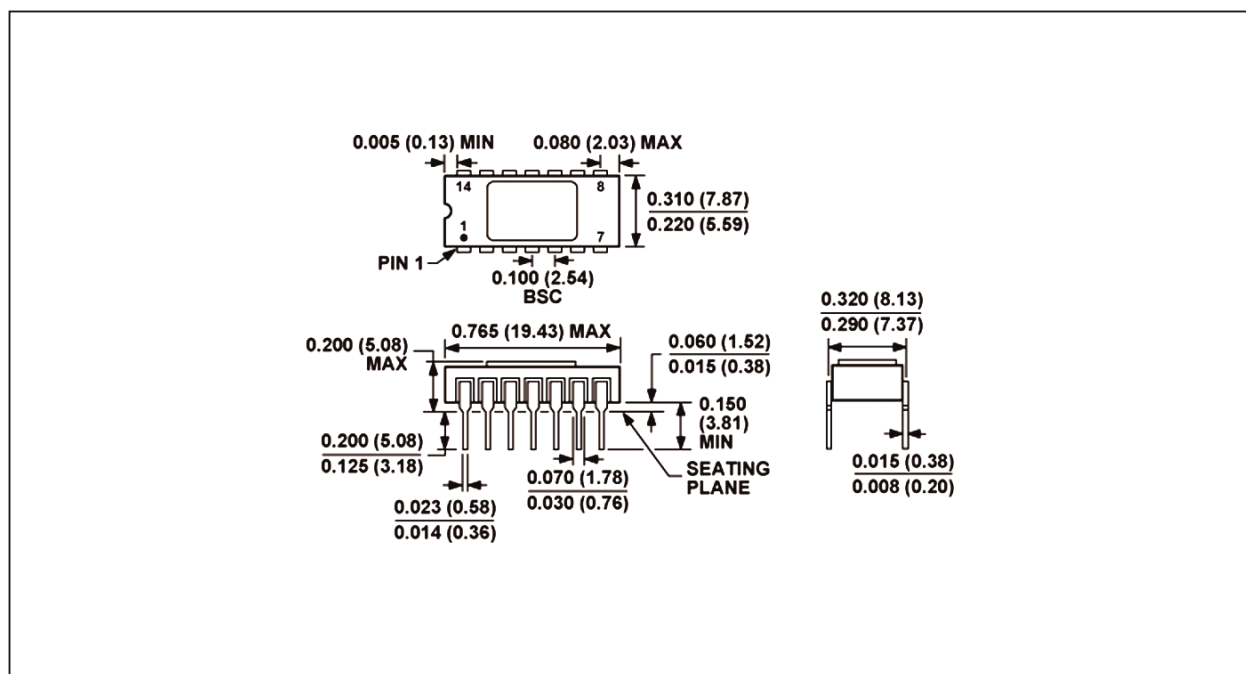


Figure 8. Side-Brazed Ceramic Dual-In-Line Package Outline

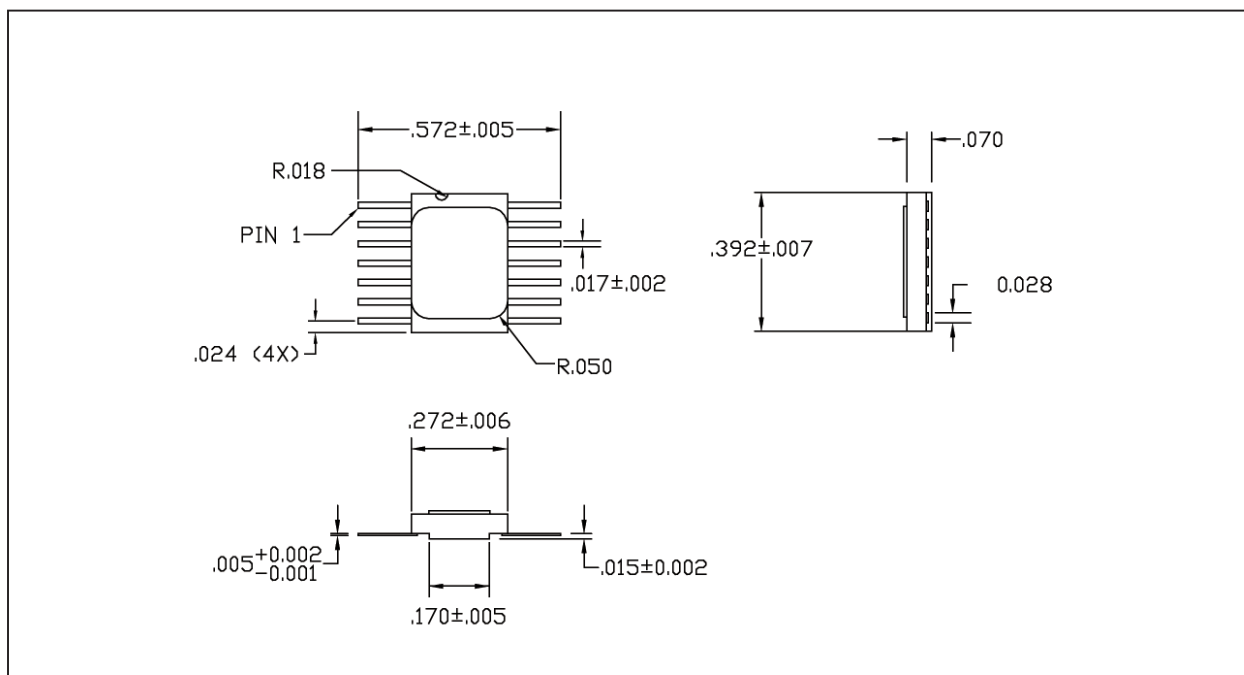


Figure 9. Ceramic Flatpack package Outline

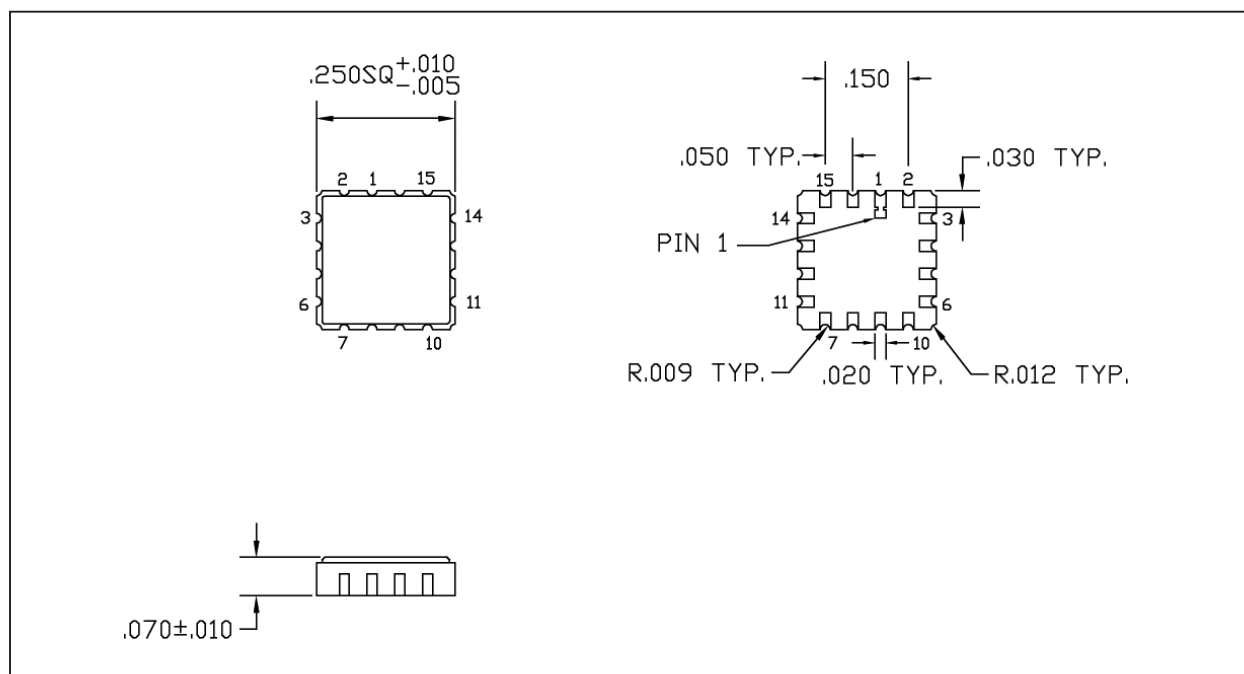


Figure 10. Ceramic LCC Package Outline

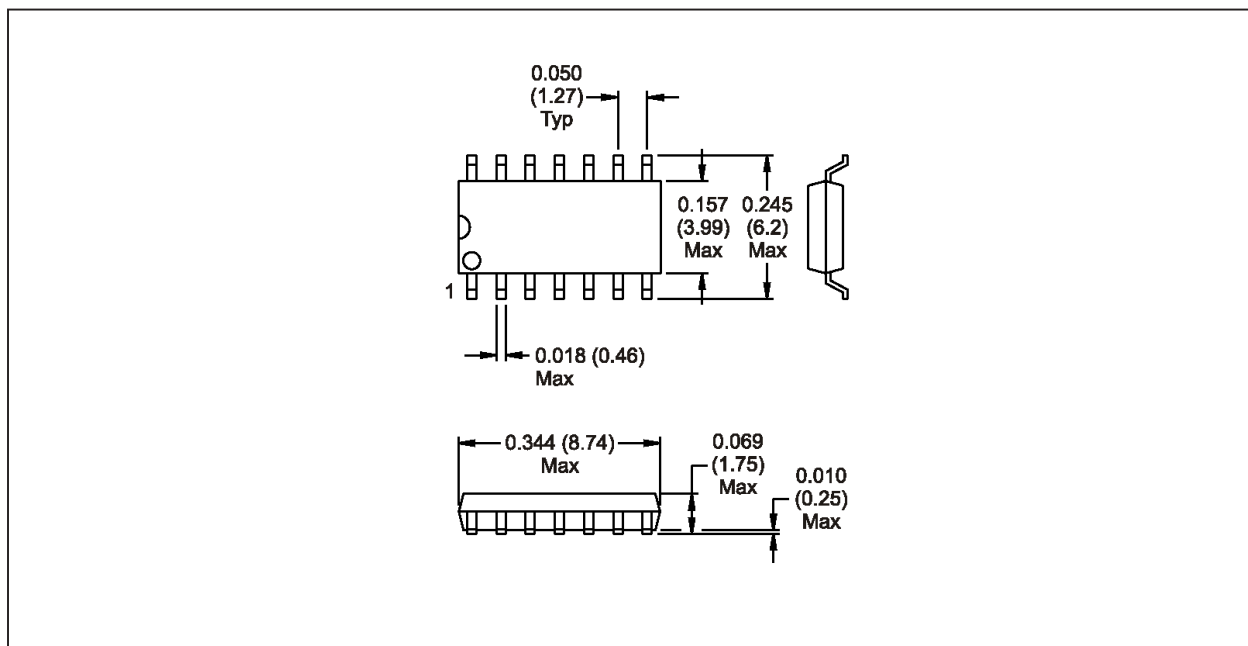


Figure 11. Surface-Mount Package Outline

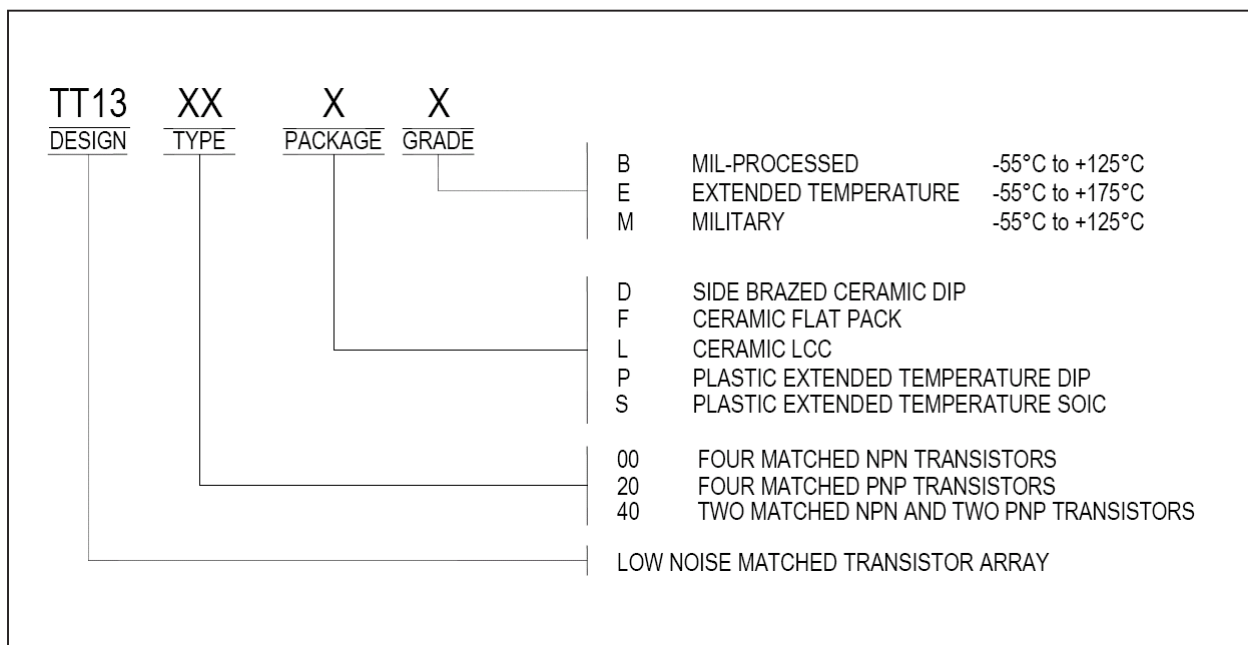


Figure 12. Ordering Information

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CAUTION: THIS IS AN ESD (ELECTROSTATIC DISCHARGE) SENSITIVE DEVICE.

It can be damaged by the currents generated by electrostatic discharge. Static charge and therefore dangerous voltages can accumulate and discharge without detection causing a loss of function or performance to occur.

The transistors in this device are unprotected in order to maximize performance and flexibility. They are more sensitive to ESD damage than many other ICs which include protection devices at their inputs. Note that all of the pins (not just the "inputs") are susceptible.

Use ESD preventative measures when storing and handling this device. Unused devices should be stored in conductive packaging. Packaging should be discharged to the destination socket before the devices are removed. ESD damage can occur to these devices even after they are installed in a board-level assembly. Circuits should include specific and appropriate ESD protection.